

ABSTRACT

A polishing apparatus is controlled to perform dressing at appropriate timing. A controller of the polishing apparatus determines, based on the state of a polishing surface of a polishing pad measured by a measurement device, estimated timing when the degree of polishing capability of the polishing pad is expected to be fallen below a threshold level; identifies, from multiple free time slots in an operation schedule, a free time slot positioned just before the estimated timing; and makes a dressing device apply a dressing process to the polishing pad in the identified free time slot.

Selected Drawing: Fig. 7